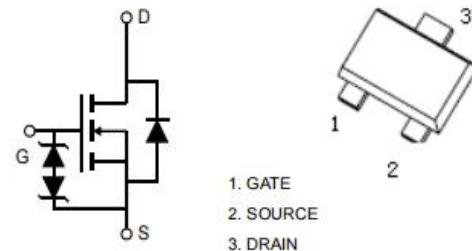


**SOT-723 20V N Channel Enhancement ESD Protection 沟道增强型带静电保护  
MOS Field Effect Transistor 场效应管**



**■ Absolute Maximum Ratings 最大额定值**

Characteristic 特性参数	Symbol 符号	Rating 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	$BV_{DSS}$	20	V
Gate- Source Voltage 栅极-源极电压	$V_{GS}$	$\pm 10$	V
Drain Current (continuous)漏极电流-连续	$I_D$ (at $T_A = 25^\circ C$ )	0.8	A
Drain Current (pulsed)漏极电流-脉冲	$I_{DM}$	1.8	A
Total Device Dissipation 总耗散功率	$P_D$ (at $T_A = 25^\circ C$ )	150	mW
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	850	°C/W
ESD Protected Up to 人体模式静电保护范围	ESD(HBM)	2.0	kV
Junction/Storage Temperature 结温/储存温度	$T_J, T_{stg}$	-55~150	°C

**■ Device Marking 产品字标**

FS3134KT7=KF

## ■ Electrical Characteristics 电特性

( $T_A=25^\circ\text{C}$  unless otherwise noted 如无特殊说明, 温度为  $25^\circ\text{C}$ )

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压( $I_D=250\mu\text{A}, V_{GS}=0\text{V}$ )	$\text{BV}_{\text{DSS}}$	20	—	—	V
Gate Threshold Voltage 栅极开启电压( $I_D=250\mu\text{A}, V_{GS}=V_{DS}$ )	$V_{GS(\text{th})}$	0.45	0.6	1	V
Zero Gate Voltage Drain Current 零栅压漏极电流( $V_{GS}=0\text{V}, V_{DS}=20\text{V}$ )	$I_{\text{DSS}}$	—	—	1	$\mu\text{A}$
Gate Body Leakage 栅极漏电流( $V_{GS}=\pm 10\text{V}, V_{DS}=0\text{V}$ )	$I_{\text{GSS}}$	—	—	$\pm 10$	$\mu\text{A}$
Static Drain-Source On-State Resistance 静态漏源导通电阻( $I_D=0.5\text{A}, V_{GS}=4.5\text{V}$ ) ( $I_D=0.5\text{A}, V_{GS}=2.5\text{V}$ )	$R_{\text{DS}(\text{ON})}$	—	130 200	200 300	$\text{m}\Omega$
Diode Forward Voltage Drop 内附二极管正向压降( $I_{SD}=0.8\text{A}, V_{GS}=0\text{V}$ )	$V_{\text{SD}}$	—	0.8	1	V
Input Capacitance 输入电容 ( $V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$ )	$C_{\text{ISS}}$	—	48	—	pF
Common Source Output Capacitance 共源输出电容( $V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$ )	$C_{\text{OSS}}$	—	13	—	pF
Reverse Transfer Capacitance 反馈电容( $V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$ )	$C_{\text{RSS}}$	—	8	—	pF
Total Gate Charge 棚极电荷密度 ( $V_{DS}=10\text{V}, I_D=0.25\text{A}, V_{GS}=4.5\text{V}$ )	$Q_g$	—	0.75	—	nC
Gate Source Charge 棚源电荷密度 ( $V_{DS}=10\text{V}, I_D=0.25\text{A}, V_{GS}=4.5\text{V}$ )	$Q_{gs}$	—	0.075	—	nC
Gate Drain Charge 棚漏电荷密度 ( $V_{DS}=10\text{V}, I_D=0.25\text{A}, V_{GS}=4.5\text{V}$ )	$Q_{gd}$	—	0.225	—	nC
Turn-ON Delay Time 开启延迟时间 ( $V_{DS}=10\text{V}, I_D=0.5\text{A}, R_{\text{GEN}}=10\Omega, V_{GS}=4.5\text{V}$ )	$t_{d(\text{on})}$	—	3.6	—	ns
Turn-ON Rise Time 开启上升时间 ( $V_{DS}=10\text{V}, I_D=0.5\text{A}, R_{\text{GEN}}=10\Omega, V_{GS}=4.5\text{V}$ )	$t_r$	—	4.3	—	ns
Turn-OFF Delay Time 关断延迟时间 ( $V_{DS}=10\text{V}, I_D=0.5\text{A}, R_{\text{GEN}}=10\Omega, V_{GS}=4.5\text{V}$ )	$t_{d(\text{off})}$	—	12.1	—	ns
Turn-OFF Fall Time 关断下降时间 ( $V_{DS}=10\text{V}, I_D=0.5\text{A}, R_{\text{GEN}}=10\Omega, V_{GS}=4.5\text{V}$ )	$t_f$	—	4.3	—	ns

## ■Typical Characteristic Curve 典型特性曲线

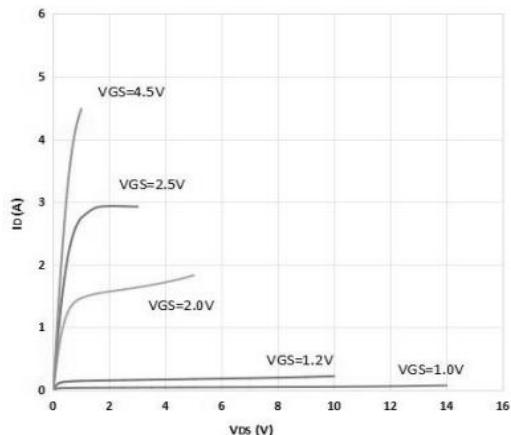


Figure 1: Output Characteristics

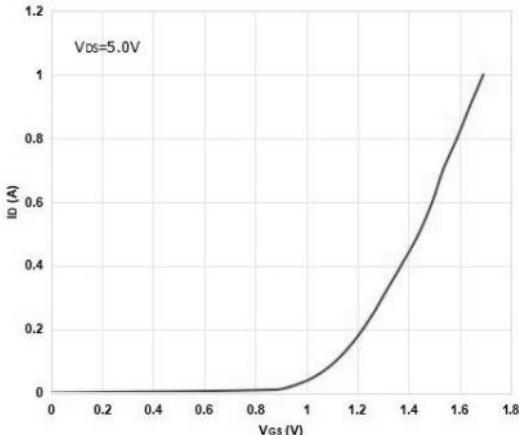


Figure 2: Transfer Characteristics

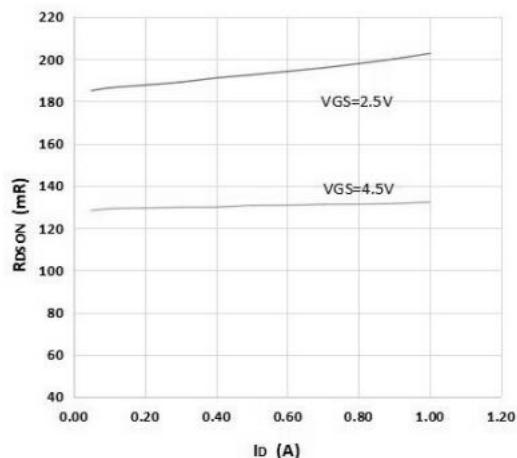


Figure 3: On-Resistance vs. Drain Current

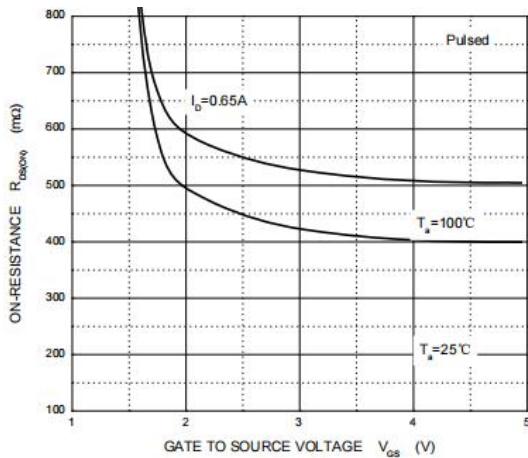


Figure 4: On-Resistance vs.  $V_{GS}$

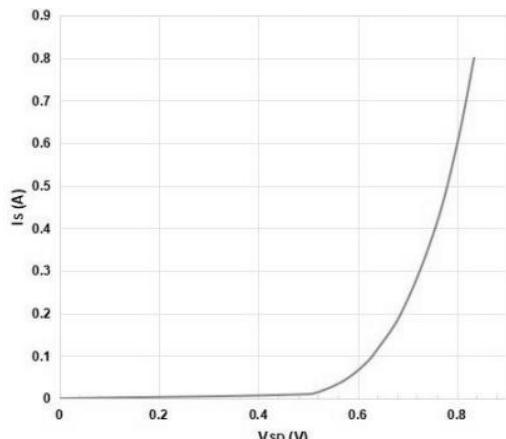


Figure 5: Diode Characteristics

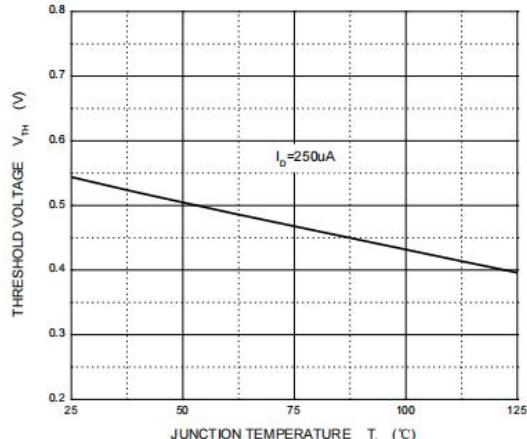
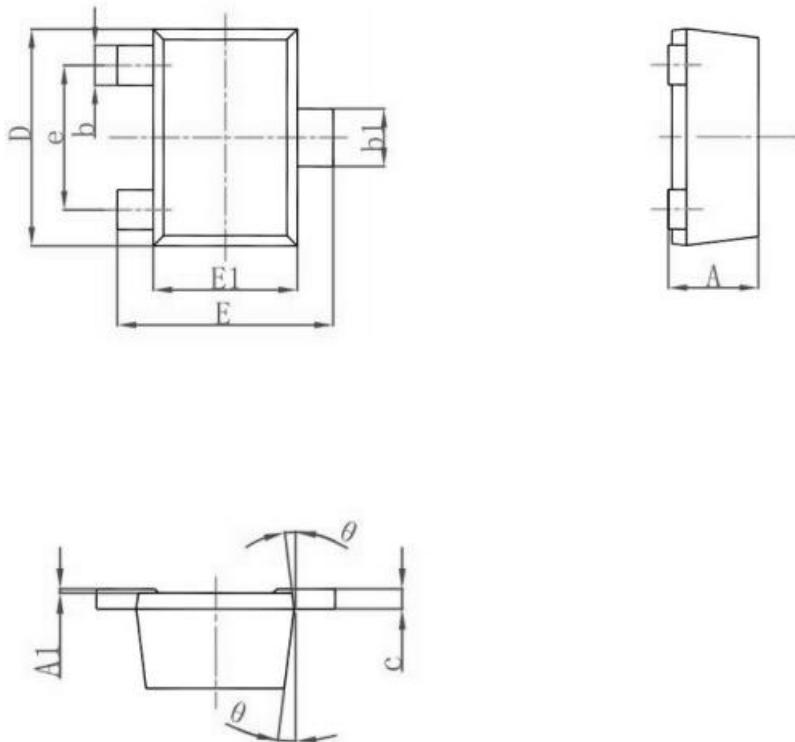


Figure 6: Threshold Characteristics

■ Dimension 外形封装尺寸



Symbol	Dimensions In Millimet	
	Min	Max
A	0.40	0.50
A1	0.00	0.10
b	0.15	0.25
b1	0.20	0.30
c	0.06	0.16
D	1.10	1.30
e	0.8TYP	
E	1.10	1.30
E1	0.70	0.90
θ	8°	10°